COMPTEST
Services LLC

EXHIBIT 13 APPENDIX C: T-COIL DATA PLOT

CELL BC-0

Test Laboratory: COMPTEST/KYOCERA   Date: 01/17/2013

FCC_S2151_TCoil_CELL-BC0_Ch.1013 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_1013/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.1 dB
ABM1 comp = -0.092 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_1013/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
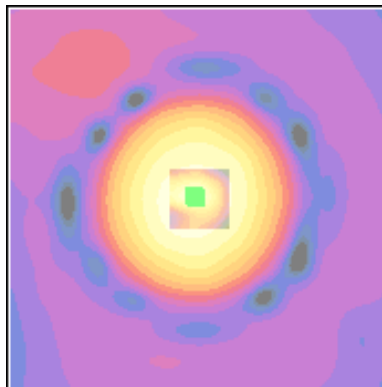Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.3 dB
ABM1 comp = -0.075 dB A/m
BWC Factor = 0.155979 dB
Location: 0.6, -0.4, 3.7 mm

0 dB = 453.8

COMPTEST Services LLC

Test Laboratory: COMPTEST/KYOCERA   Date: 01/17/2013

FCC_ S2151_TCoil_CELL-BC0 _Ch. 1013 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_1013/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.3 dB
ABM1 comp = -8.71 dB A/m
BWC Factor = 0.155979 dB
Location: -5.4, 0, 3.7 mm

General Scans_1013/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
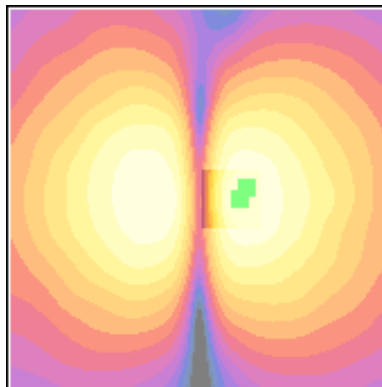Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.0 dB
ABM1 comp = -8.92 dB A/m
BWC Factor = 0.155979 dB
Location: -6.2, -1.6, 3.7 mm

0 dB = 292.5

Test Laboratory: COMPTEST/KYOCERA   Date: 01/17/2013

FCC_ S2151_TCoil_CELL-BC0 _Ch. 1013 y (transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_1013/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.3 dB
ABM1 comp = -9.24 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 8.3, 3.7 mm

General Scans_1013/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
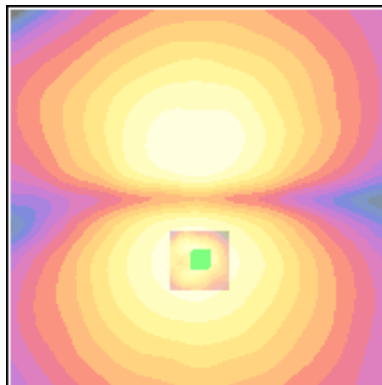Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.3 dB
ABM1 comp = -9.38 dB A/m
BWC Factor = 0.155979 dB
Location: -0.2, 7.9, 3.7 mm

0 dB = 260.1

Test Laboratory: COMPTEST/KYOCERA   Date: 01/17/2013

FCC_ S2151_TCoil_CELL-BC0_Ch.384 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_384/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.3 dB
ABM1 comp = -1.56 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, -3.3, 3.7 mm

General Scans_384/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
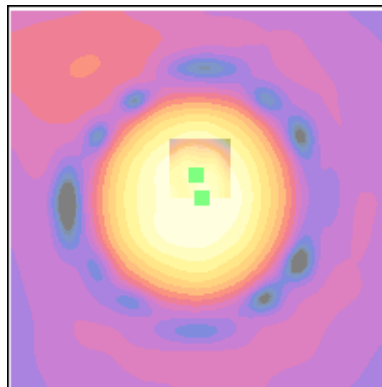Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.3 dB
ABM1 comp = -0.679 dB A/m
BWC Factor = 0.155979 dB
Location: -0.2, -0.2, 3.7 mm

0 dB = 367.1

Test Laboratory: COMPTEST/KYOCERA   Date: 01/17/2013

FCC_ S2151_TCoil_CELL-BC0 _Ch.384 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ⬜⬜⬜ 1 deg C, Liquid T = 22.0 ⬜⬜⬜ 1 deg C

General Scans_384/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.0 dB
ABM1 comp = -8.92 dB A/m
BWC Factor = 0.155979 dB
Location: 5.8, 0, 3.7 mm

General Scans_384/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
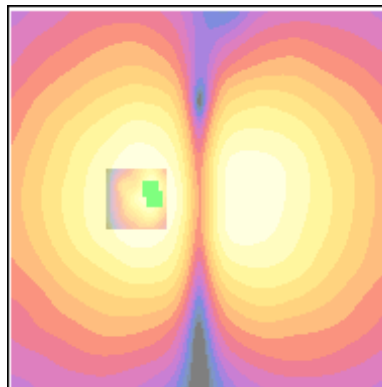Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.3 dB
ABM1 comp = -8.42 dB A/m
BWC Factor = 0.155979 dB
Location: 6.3, -1.4, 3.7 mm

0 dB = 280.5

Test Laboratory: COMPTEST/KYOCERA   Date: 01/17/2013

FCC_ S2151_TCoil_CELL-BC0 _Ch.384 y(transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_384/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -9.26 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, -7.5, 3.7 mm

General Scans_384/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
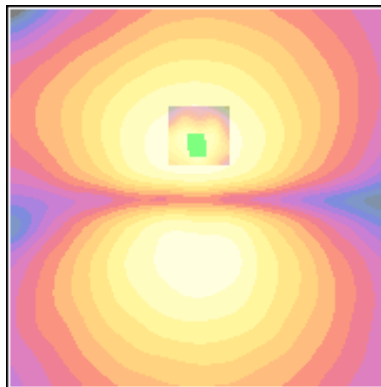Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -9.27 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, -6.5, 3.7 mm

0 dB = 257.8

Test Laboratory: COMPTEST/KYOCERA   Date: 01/17/2013

FCC_ S2151_TCoil_CELL-BC0_Ch. 777 z(axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_777/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.7 dB
ABM1 comp = -1.05 dB A/m
BWC Factor = 0.155041 dB
Location: 2.9, 0.8, 3.7 mm

General Scans_777/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
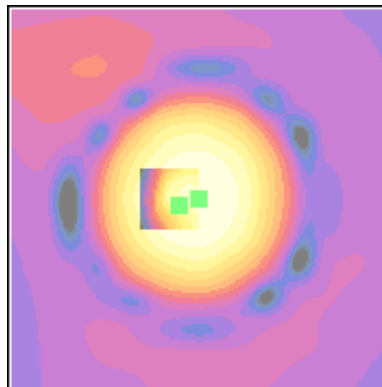Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.7 dB
ABM1 comp = -0.530 dB A/m
BWC Factor = 0.155041 dB
Location: 0.2, 0, 3.7 mm

0 dB = 386.0

Test Laboratory: COMPTEST/KYOCERA   Date: 01/17/2013

FCC_ S2151_TCoil_CELL- BC0_Ch. 777 x(longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_777/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.1 dB
ABM1 comp = -8.53 dB A/m
BWC Factor = 0.155041 dB
Location: 7.1, -0.4, 3.7 mm

General Scans_777/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
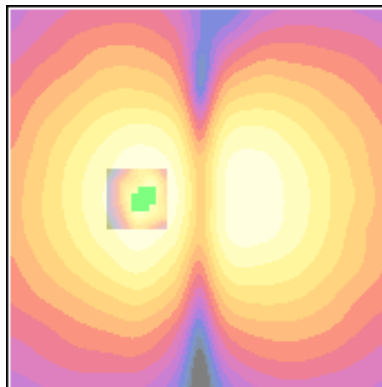Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -8.43 dB A/m
BWC Factor = 0.155041 dB
Location: 7.9, 0.4, 3.7 mm

0 dB = 284.8

Test Laboratory: COMPTEST/KYOCERA   Date: 01/17/2013

FCC_ S2151_TCoil_CELL- BC0_Ch. 777 y(transveral)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_777/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.4 dB
ABM1 comp = -9.32 dB A/m
BWC Factor = 0.155041 dB
Location: 0.8, -5.8, 3.7 mm

General Scans_777/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
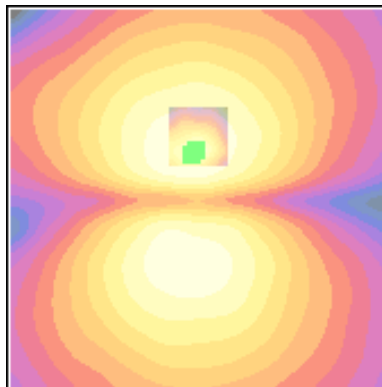Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.6 dB
ABM1 comp = -9.12 dB A/m
BWC Factor = 0.155041 dB
Location: 0.2, -6.5, 3.7 mm

0 dB = 262.0

CELL-BC10

Test Laboratory: COMPTEST/KYOCERA   Date: 01/21/13

FCC_ S2151_TCoil_CELL-BC10_Ch. 476 z(axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_476/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.0 dB
ABM1 comp = -2.25 dB A/m
BWC Factor = 0.155041 dB
Location: 0, -2.1, 3.7 mm

General Scans_476/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.4 dB
ABM1 comp = -1.37 dB A/m
BWC Factor = 0.155041 dB
Location: 0, -0.2, 3.7 mm

0 dB = 353.1

Test Laboratory: COMPTEST/KYOCERA   Date: 01/21/13

FCC_ S2151_TCoil_CELL-BC10_Ch. 476 x(longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_476/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.9 dB
ABM1 comp = -9.66 dB A/m
BWC Factor = 0.155041 dB
Location: 6.7, -0.8, 3.7 mm

General Scans_476/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
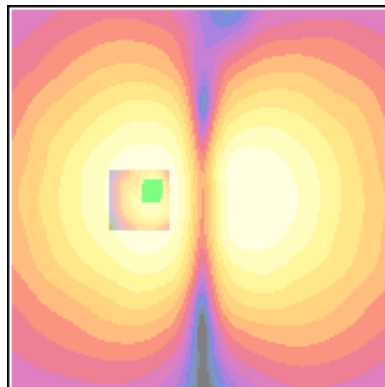Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.6 dB
ABM1 comp = -9.25 dB A/m
BWC Factor = 0.155041 dB
Location: 6.5, -1.6, 3.7 mm

0 dB = 249.3

Test Laboratory: COMPTEST/KYOCERA   Date: 01/21/13

FCC_ S2151_TCoil_CELL-BC10_Ch. 476 y(transveral)
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_476/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.4 dB
ABM1 comp = -10.6 dB A/m
BWC Factor = 0.155041 dB
Location: 0, 8.3, 3.7 mm

General Scans_476/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
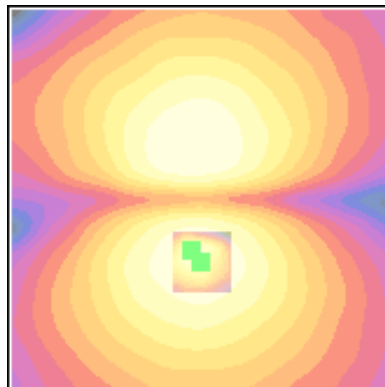Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.5 dB
ABM1 comp = -10.3 dB A/m
BWC Factor = 0.155041 dB
Location: 1.4, 6.9, 3.7 mm

0 dB = 233.2

Test Laboratory: COMPTEST/KYOCERA   Date: 01/21/13

FCC_ S2151_TCoil_CELL-BC10_Ch. 580 z(axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_580/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.1 dB
ABM1 comp = -0.149 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, 0, 3.7 mm

General Scans_580/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
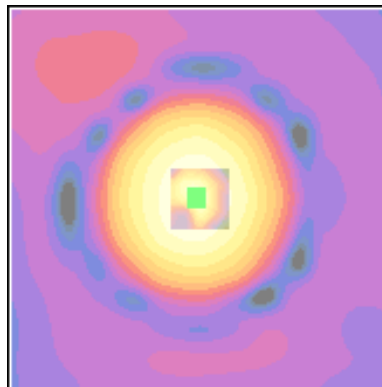Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.4 dB
ABM1 comp = 0.013 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, -0.4, 3.7 mm

0 dB = 449.5

Test Laboratory: COMPTEST/KYOCERA   Date: 01/21/13

FCC_ S2151_TCoil_CELL-BC10_Ch. 580 x(longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m³
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_580/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -8.57 dB A/m
BWC Factor = 0.155041 dB
Location: 6.7, 0, 3.7 mm

General Scans_580/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
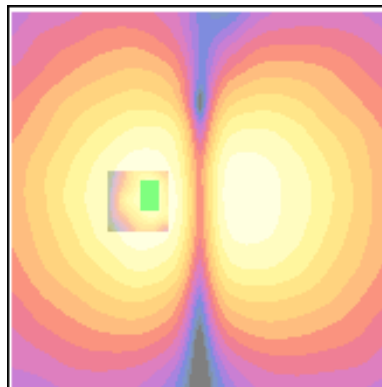BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.3 dB
ABM1 comp = -8.58 dB A/m
BWC Factor = 0.155041 dB
Location: 6.5, -1.4, 3.7 mm

0 dB = 290.0

Test Laboratory: COMPTEST/KYOCERA   Date: 01/21/13

FCC_ S2151_TCoil_CELL-BC10_Ch. 580 y(transveral)
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_580/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.9 dB
ABM1 comp = -9.66 dB A/m
BWC Factor = 0.155041 dB
Location: 0, -6.3, 3.7 mm

General Scans_580/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
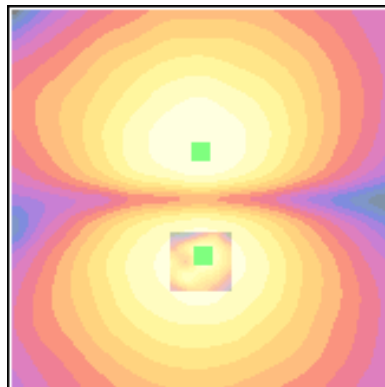Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.0 dB
ABM1 comp = -9.53 dB A/m
BWC Factor = 0.155041 dB
Location: -0.4, 7.5, 3.7 mm

0 dB = 247.4

Test Laboratory: COMPTEST/KYOCERA   Date: 01/21/13

FCC_ S2151_TCoil_CELL-BC10_Ch. 684 z(axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_684/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.1 dB
ABM1 comp = -0.119 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, 0.8, 3.7 mm

General Scans_684/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
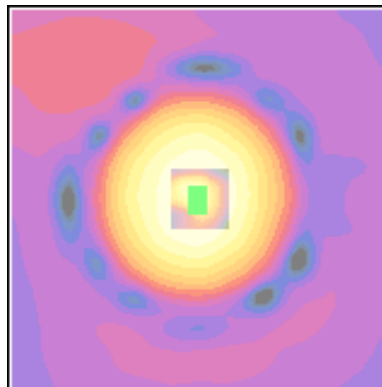Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.5 dB
ABM1 comp = 0.173 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, -0.4, 3.7 mm

0 dB = 402.2

Test Laboratory: COMPTEST/KYOCERA   Date: 01/21/13

FCC_ S2151_TCoil_CELL-BC10_Ch. 684 x(longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_684/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.6 dB
ABM1 comp = -8.62 dB A/m
BWC Factor = 0.155041 dB
Location: 6.3, 0.8, 3.7 mm

General Scans_684/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
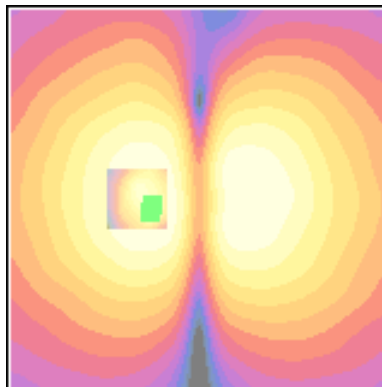Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.6 dB
ABM1 comp = -8.19 dB A/m
BWC Factor = 0.155041 dB
Location: 6.3, 1.6, 3.7 mm

0 dB = 270.5

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Test Laboratory: COMPTEST/KYOCERA   Date: 01/21/13

FCC_ S2151_TCoil_CELL-BC10_Ch. 684 y(transveral)
FCC_S2151_TCoil_CELL BC10_012113
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_684/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.8 dB
ABM1 comp = -9.00 dB A/m
BWC Factor = 0.155041 dB
Location: 0, 8.3, 3.7 mm

General Scans_684/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
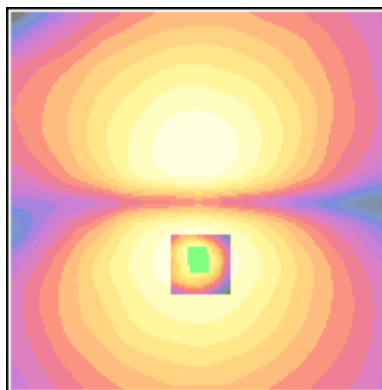Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.5 dB
ABM1 comp = -9.25 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, 7.1, 3.7 mm

0 dB = 275.5

PCS

Test Laboratory: COMPTEST/KYOCERA   Date: 01/16/2013

FCC_ S2151_TCoil_PCS_Ch. 25 z(axial)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.1 dB
ABM1 comp = -0.015 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 0.4, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
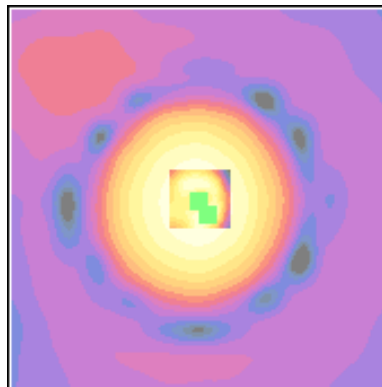Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.3 dB
ABM1 comp = -1.09 dB A/m
BWC Factor = 0.155979 dB
Location: -1, 2, 3.7 mm

0 dB = 454.2

Test Laboratory: COMPTEST/KYOCERA   Date: 01/16/2013

FCC_ S2151_TCoil_PCS_ Ch. 25 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε$_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.1 dB
ABM1 comp = -8.55 dB A/m
BWC Factor = 0.155979 dB
Location: 6.3, 0.8, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
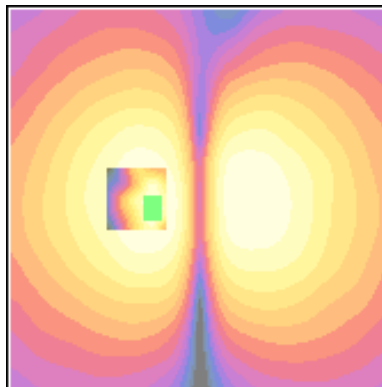Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.4 dB
ABM1 comp = -8.27 dB A/m
BWC Factor = 0.155979 dB
Location: 6.3, 1.8, 3.7 mm

0 dB = 285.9

COMPTEST Services LLC

Test Laboratory: COMPTEST/KYOCERA   Date: 01/16/2013

FCC_ S2151_TCoil_PCS_ Ch. 25 y(transversal)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -9.50 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 9.2, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
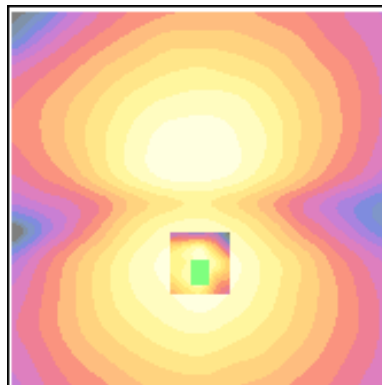Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -9.47 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, 9.9, 3.7 mm

0 dB = 255.6

Test Laboratory: COMPTEST/KYOCERA   Date: 01/16/2013

FCC_ S2150_TCoil_PCS Ch. 600 z(axial)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.1 dB
ABM1 comp = -0.875 dB A/m
BWC Factor = 0.155041 dB
Location: 0.8, 2.9, 3.7 mm

General Scans_600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
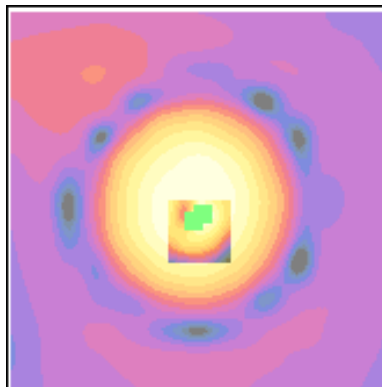Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.8 dB
ABM1 comp = -0.390 dB A/m
BWC Factor = 0.155041 dB
Location: -0.6, 2, 3.7 mm

0 dB = 404.1

Test Laboratory: COMPTEST/KYOCERA   Date: 01/16/2013

FCC_ S2151_TCoil_PCS Ch. 600 x (longitudinal)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.2 dB
ABM1 comp = -8.34 dB A/m
BWC Factor = 0.155041 dB
Location: 5.4, 0.4, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
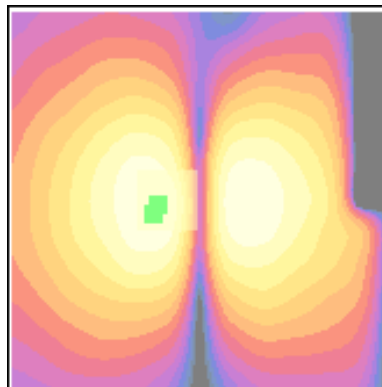Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.8 dB
ABM1 comp = -7.56 dB A/m
BWC Factor = 0.155041 dB
Location: 6.2, 1.8, 3.7 mm

0 dB = 322.5

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Test Laboratory: COMPTEST/KYOCERA   Date: 01/16/2013

FCC_ S2151_TCoil_PCS_ Ch. 600 y(transversal)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.5 dB
ABM1 comp = -9.08 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, -5, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
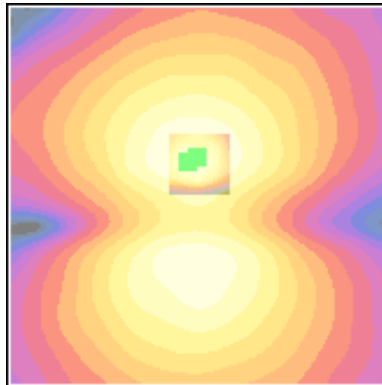Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.6 dB
ABM1 comp = -8.73 dB A/m
BWC Factor = 0.155041 dB
Location: 1.6, -4.4, 3.7 mm

0 dB = 266.6

Test Laboratory: COMPTEST/KYOCERA   Date: 01/16/2013

FCC_ S2150_TCoil_PCS_ Ch.1175 z(axial)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.9 dB
ABM1 comp = -0.069 dB A/m
BWC Factor = 0.155041 dB
Location: 0, 0.4, 3.7 mm

General Scans_1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
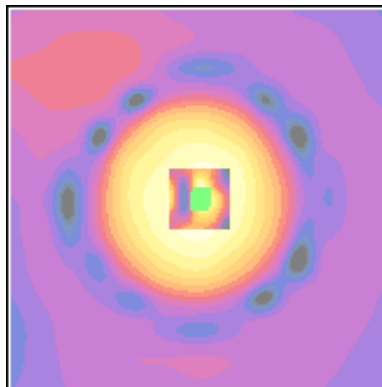Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.8 dB
ABM1 comp = -0.418 dB A/m
BWC Factor = 0.155041 dB
Location: -0.4, -0.4, 3.7 mm

0 dB = 439.6

Test Laboratory: COMPTEST/KYOCERA   Date: 01/16/2013

FCC_ S2151_TCoil_PCS _Ch. 1175 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ☐☐☐ 1 deg C, Liquid T = 22.0 ☐☐☐ 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.58
Measure Window Start: 300ms
Measure Window Length: 1000ms
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.8 dB
ABM1 comp = -8.44 dB A/m
BWC Factor = 0.155041 dB
Location: 6.7, -0.8, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
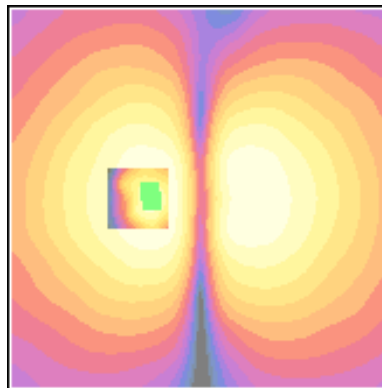Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.3 dB
ABM1 comp = -8.49 dB A/m
BWC Factor = 0.155041 dB
Location: 6.3, 0.2, 3.7 mm

0 dB = 274.1

Test Laboratory: COMPTEST/KYOCERA   Date: 01/16/2013

FCC_ S2151_TCoil_PCS_ Ch. 1175 y(transversal)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -9.66 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, -5.8, 3.7 mm

General Scans_1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
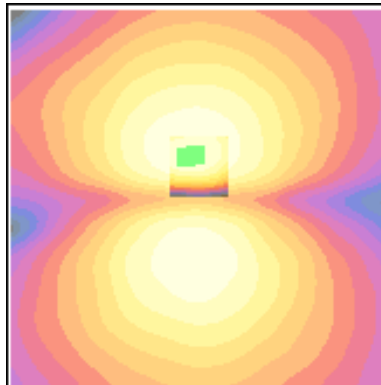Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.0 dB
ABM1 comp = -9.48 dB A/m
BWC Factor = 0.155041 dB
Location: 1.6, -5.6, 3.7 mm

0 dB = 256.3